

Application No. 09/09/746,774

IN THE CLAIMS:

Please substitute amended Claims 1-4 for pending Claims 1-4 as

follows:

Sub C3 (Amended) An improved process for manufacture and assembly of a plurality of adjoining printed wiring boards, comprising:

(a) forming at least a first circuit pattern and a second circuit pattern on a common substrate;

(b) connecting at least the first circuit pattern to the second circuit pattern;

(c) separating the common substrate into at least a first substrate and a second substrate with the first substrate including the first circuit pattern thereon and the second substrate including the second circuit pattern thereon; and

B3 (d) tilting the first substrate relative to the second substrate while maintaining the connection between the first circuit pattern and the second circuit pattern.

2) (Amended) The process of claim 1, further comprising scoring the common substrate along a dividing line.

3) (Amended) The process of claim 1, further comprising holding the separated substrates in fixed position relative to each other by a holding fixture.

Sub C3 4) (Amended) The process of claim 1, further comprising testing the connection between the first and second circuit patterns prior to the step of separating the common substrate into separate substrates.